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Data Sheet | September 2013

N-Channel Power MOSFET
60V, 50A, 22 mΩ

These N-Channel power MOSFETs are manufactured using the MegaFET process. This process, which uses feature sizes approaching those of LSI integrated circuits gives optimum utilization of silicon, resulting in outstanding performance. They were designed for use in applications such as switching regulators, switching converters, motor drivers, and relay drivers. These transistors can be operated directly from integrated circuits.

Formerly developmental type TA49018.

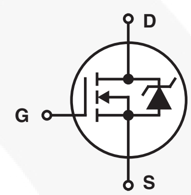
Ordering Information

PART NUMBER	PACKAGE	BRAND
RFP50N06	TO-220AB	RFP50N06

Features

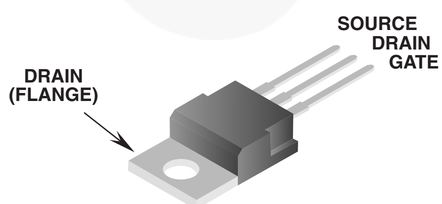
- 50A, 60V
- $r_{DS(ON)}$ = 0.022Ω
- Temperature Compensating PSPICE® Model
- Peak Current vs Pulse Width Curve
- UIS Rating Curve
- 175°C Operating Temperature

Symbol



Packaging

JEDEC TO-220AB



Absolute Maximum Ratings $T_C = 25^oC$, Unless Otherwise Specified

		RFP50N06	UNITS
Drain to Source Voltage (Note 1)	V_{DSS}	60	V
Drain to Gate Voltage ($R_{GS} = 20k\Omega$) (Note 1)	V_{DGR}	60	V
Gate to Source Voltage	V_{GS}	±20	V
Continuous Drain Current (Figure 2)	I_D	50	A
Pulsed Drain Current	I_{DM}	(Figure 5)	
Pulsed Avalanche Rating	E_{AS}	(Figure 6)	
Power Dissipation	P_D	131	W
Linear Derating Factor		0.877	W/^{o}C
Operating and Storage Temperature	T_J, T_{STG}	-55 to 175	^{o}C
Maximum Temperature for Soldering			
Leads at 0.063in (1.6mm) from Case for 10s	T_L	300	^{o}C
Package Body for 10s, see Techbrief 334	T_{pkg}	260	^{o}C

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

NOTE:

1. $T_J = 25^oC$ to 150^oC.

Electrical Specifications $T_C = 25^oC$, Unless Otherwise Specified

PARAMETER	SYMBOL	TEST CONDITIONS		MIN	TYP	MAX	UNITS
Drain to Source Breakdown Voltage	BV_{DSS}	$I_D = 250\mu A$, $V_{GS} = 0V$ (Figure 11)		60	-	-	V
Gate to Source Threshold Voltage	$V_{GS(TH)}$	$V_{GS} = V_{DS}$, $I_D = 250\mu A$ (Figure 10)		2	-	4	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 60V$, $V_{GS} = 0V$	$T_C = 25^oC$	-	-	1	µA
			$T_C = 150^oC$	-	-	50	µA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 20V$		-	-	±100	nA
Drain to Source On Resistance	$r_{DS(ON)}$	$I_D = 50A$, $V_{GS} = 10V$ (Figures 9)		-	-	0.022	Ω
Turn-On Time	t_{ON}	$V_{DD} = 30V$, $I_D = 50A$ $R_L = 0.6\Omega$, $V_{GS} = 10V$ $R_{GS} = 3.6\Omega$ (Figure 13)		-	-	95	ns
Turn-On Delay Time	$t_{d(ON)}$			-	12	-	ns
Rise Time	t_r			-	55	-	ns
Turn-Off Delay Time	$t_{d(OFF)}$			-	37	-	ns
Fall Time	t_f			-	13	-	ns
Turn-Off Time	t_{OFF}			-	-	75	ns
Total Gate Charge	$Q_{g(TOT)}$	$V_{GS} = 0$ to $20V$	$V_{DD} = 48V$, $I_D = 50A$, $R_L = 0.96\Omega$ $I_{g(REF)} = 1.45mA$ (Figure 13)	-	125	150	nC
Gate Charge at 10V	$Q_{g(10)}$	$V_{GS} = 0$ to $10V$		-	67	80	nC
Threshold Gate Charge	$Q_{g(TH)}$	$V_{GS} = 0$ to $2V$		-	3.7	4.5	nC
Input Capacitance	C_{ISS}	$V_{DS} = 25V$, $V_{GS} = 0V$ f = 1MHz (Figure 12)		-	2020	-	pF
Output Capacitance	C_{OSS}			-	600	-	pF
Reverse Transfer Capacitance	C_{RSS}			-	200	-	pF
Thermal Resistance Junction to Case	$R_{\theta JC}$	(Figure 3)		-	-	1.14	^{o}C/W
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	TO-220		-	-	62	^{o}C/W
		-		-	-	-	-

Source to Drain Diode Specifications

PARAMETER	SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
Source to Drain Diode Voltage	V_{SD}	$I_{SD} = 50A$	-	-	1.5	V
Reverse Recovery Time	t_{rr}	$I_{SD} = 50A$, $dI_{SD}/dt = 100A/\mu s$	-	-	125	ns

Typical Performance Curves Unless Otherwise Specified

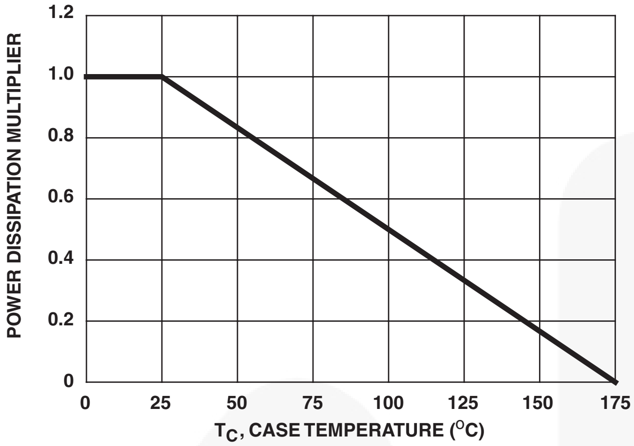


FIGURE 1. NORMALIZED POWER DISSIPATION vs CASE TEMPERATURE

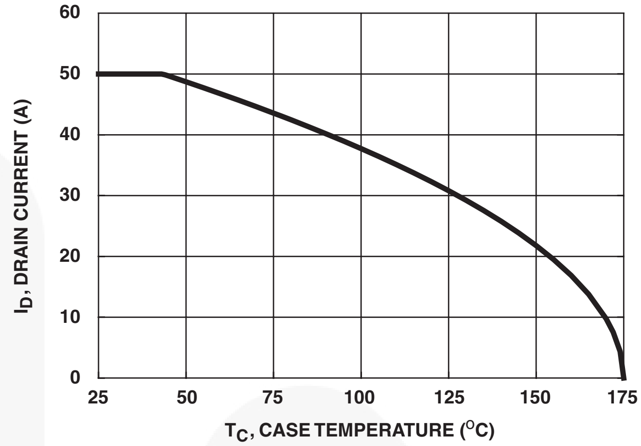


FIGURE 2. MAXIMUM CONTINUOUS DRAIN CURRENT vs CASE TEMPERATURE

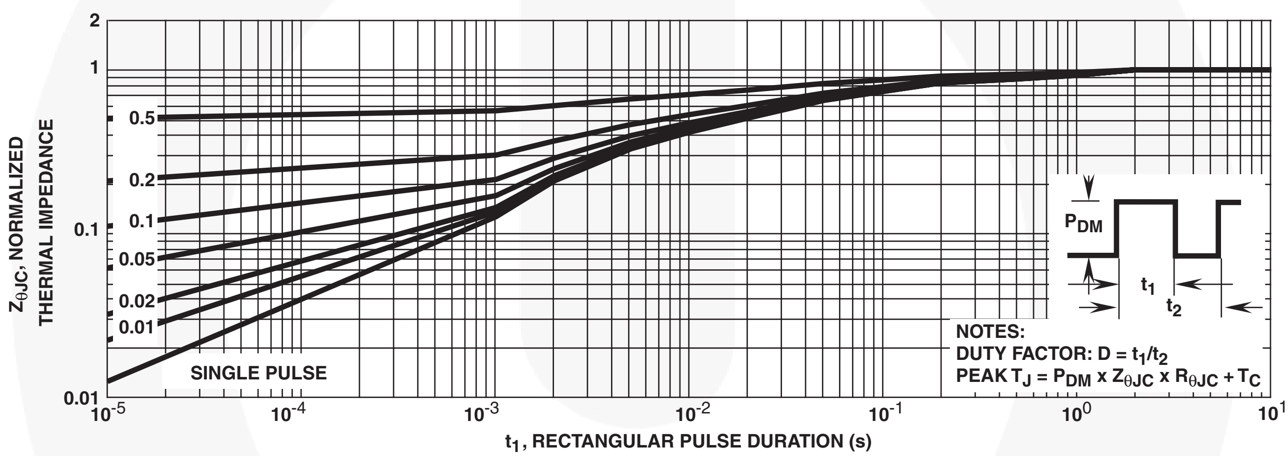


FIGURE 3. NORMALIZED MAXIMUM TRANSIENT THERMAL IMPEDANCE

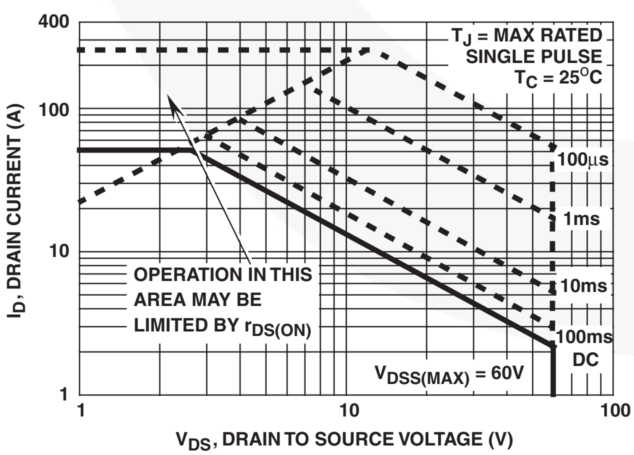


FIGURE 4. FORWARD BIAS SAFE OPERATING AREA

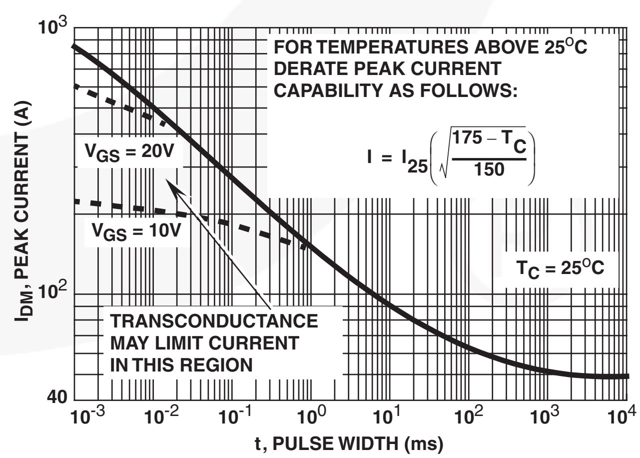
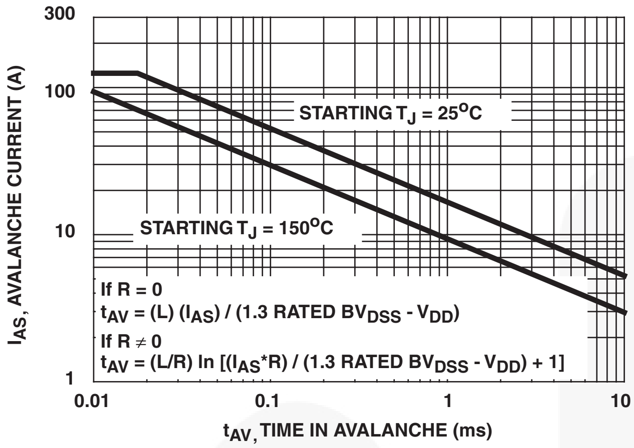


FIGURE 5. PEAK CURRENT CAPABILITY

Typical Performance Curves Unless Otherwise Specified **(Continued)**



NOTE: Refer to Fairchild Application Notes 9321 and 9322.

FIGURE 6. UNCLAMPED INDUCTIVE SWITCHING CAPABILITY

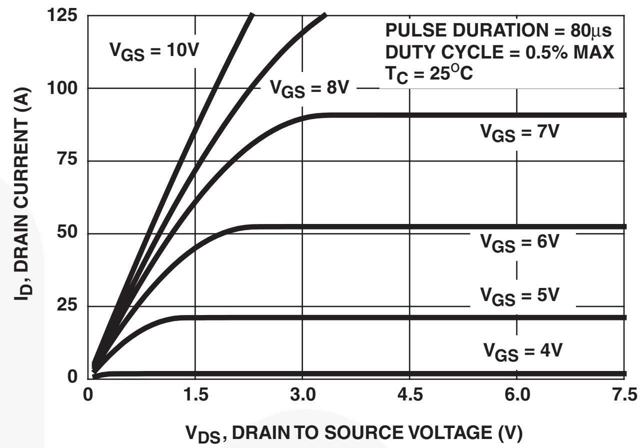


FIGURE 7. SATURATION CHARACTERISTICS

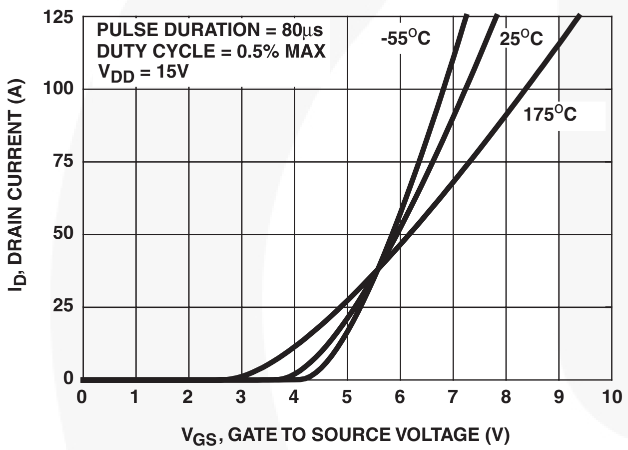


FIGURE 8. TRANSFER CHARACTERISTICS

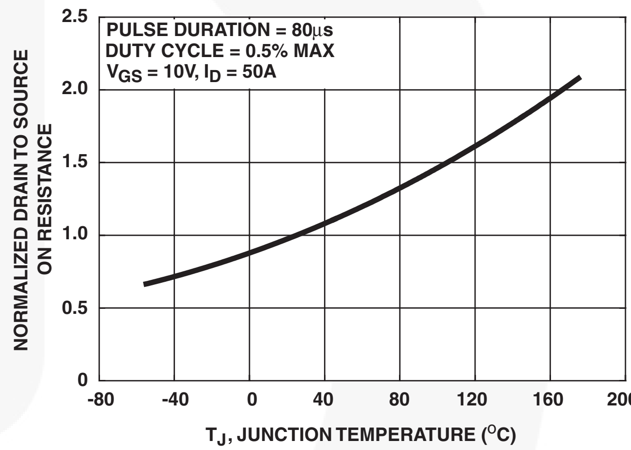


FIGURE 9. NORMALIZED DRAIN TO SOURCE ON RESISTANCE vs JUNCTION TEMPERATURE

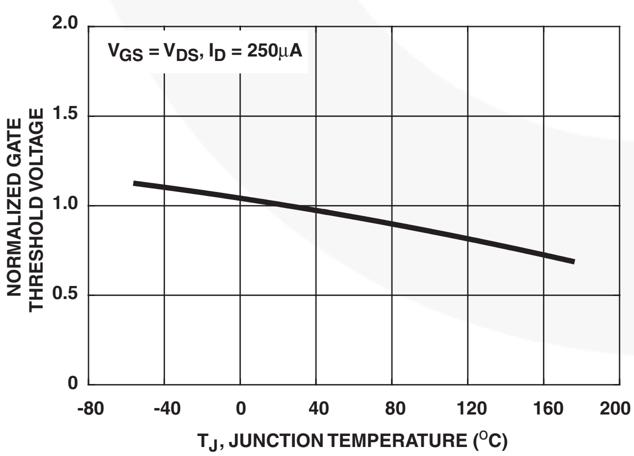


FIGURE 10. NORMALIZED GATE THRESHOLD VOLTAGE vs JUNCTION TEMPERATURE

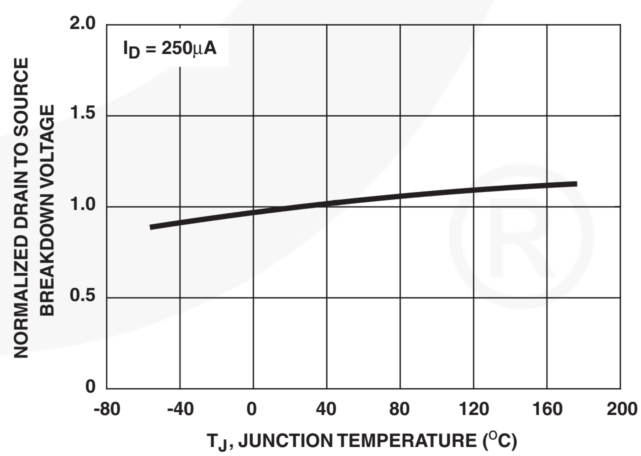


FIGURE 11. NORMALIZED DRAIN TO SOURCE BREAKDOWN VOLTAGE vs JUNCTION TEMPERATURE

Typical Performance Curves Unless Otherwise Specified (Continued)

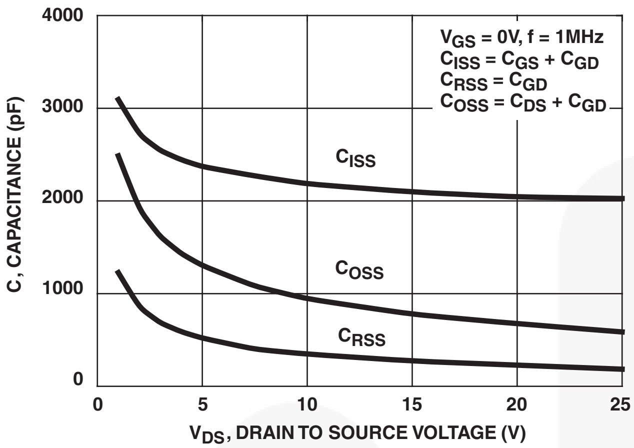
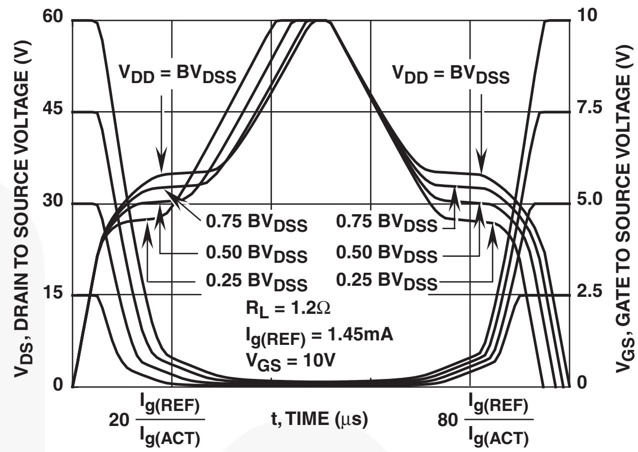


FIGURE 12. CAPACITANCE vs DRAIN TO SOURCE VOLTAGE



NOTE: Refer to Fairchild Application Notes AN7254 and AN7260.

FIGURE 13. NORMALIZED SWITCHING WAVEFORMS FOR CONSTANT GATE CURRENT

Test Circuits and Waveforms

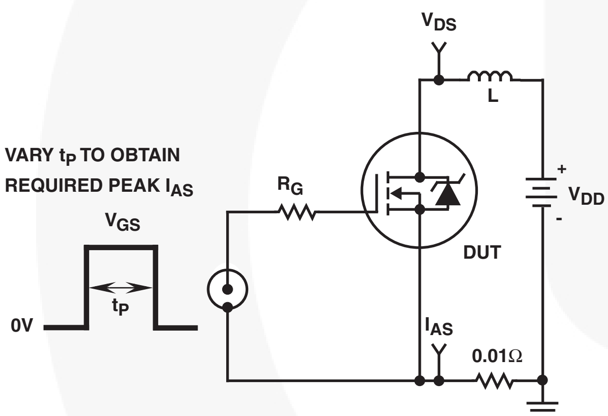


FIGURE 14. UNCLAMPED ENERGY TEST CIRCUIT

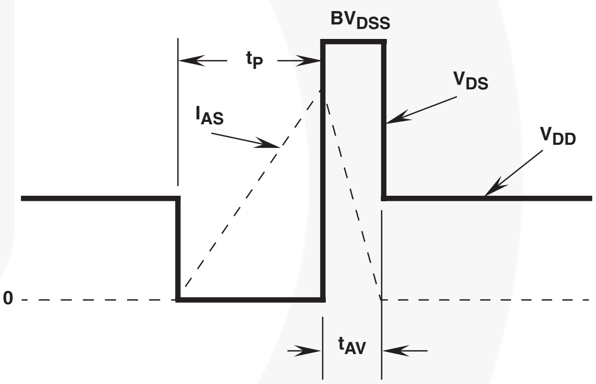


FIGURE 15. UNCLAMPED ENERGY WAVEFORMS

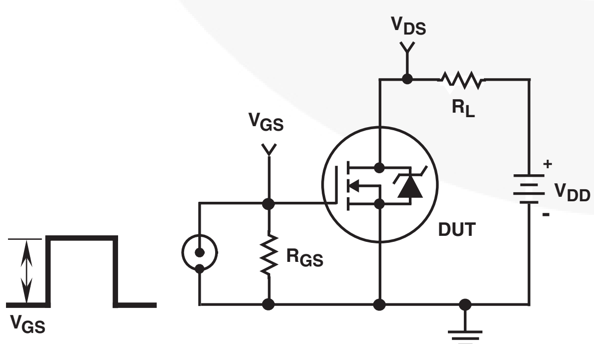


FIGURE 16. SWITCHING TIME TEST CIRCUIT

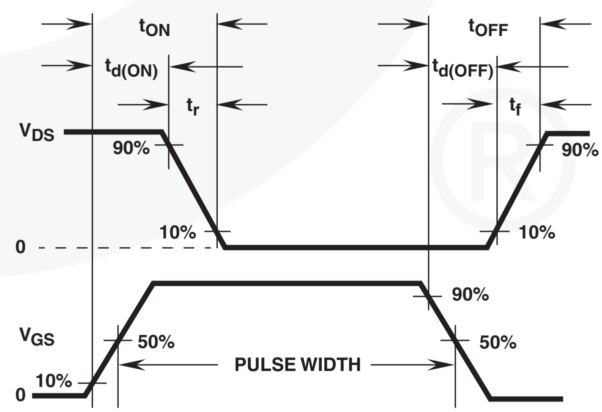


FIGURE 17. SWITCHING WAVEFORMS

Test Circuits and Waveforms (Continued)

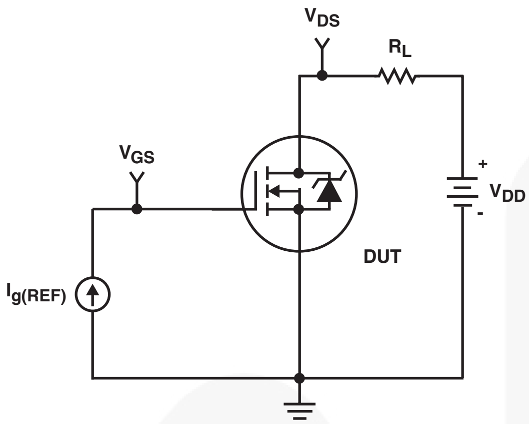


FIGURE 18. GATE CHARGE TEST CIRCUIT

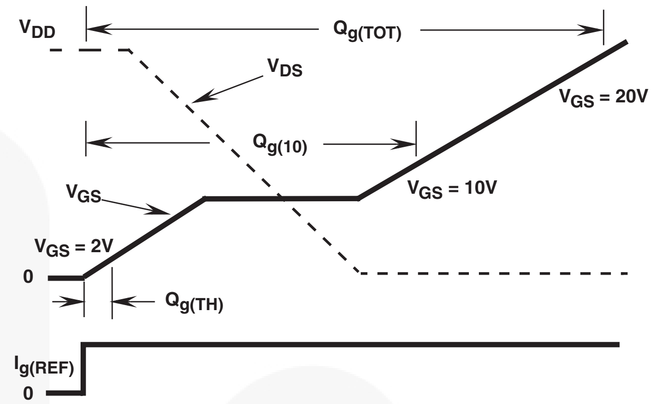


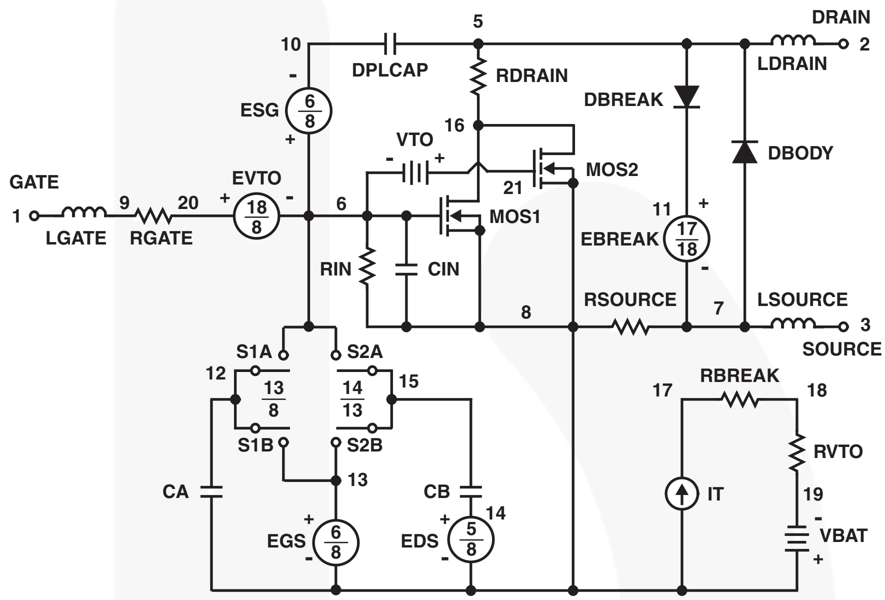
FIGURE 19. GATE CHARGE WAVEFORMS

PSPICE Electrical Model

.SUBCKT RFP50N06 2 1 3

REV 2/22/93

*NOM TEMP = 25°C



CA 12 8 3.68e-9
CB 15 14 3.625e-9
CIN 6 8 1.98e-9

DBODY 7 5 DBDMOD
DBREAK 5 11DBKMOD
DPLCAP 10 5 DPLCAPMOD

EBREAK 11 7 17 18 64.59
EDS 14 8 5 8 1
EGS 13 8 6 8 1
ESG 6 10 6 8 1
EVTO 20 6 18 8 1

IT 8 17 1

LDRAIN 2 5 1e-9
LGATE 1 9 5.65e-9
LSOURCE 3 7 4.13e-9

MOS1 16 6 8 8 MOSMOD M=0.99
MOS2 16 21 8 8 MOSMOD M=0.01

RBREAK 17 18 RBKMOD 1
RDRAIN 5 16 RDSMOD 1e-4
RGATE 9 20 0.690
RIN 6 8 1e9
RSOURCE 8 7 RDSMOD 12e-3
RVTO 18 19 RVTOMOD 1

S1A 6 12 13 8 S1AMOD
S1B 13 12 13 8 S1BMOD
S2A 6 15 14 13 S2AMOD
S2B 13 15 14 13 S2BMOD

VBAT 8 19 DC 1
VTO 21 6 0.678

.MODEL DBDMOD D (IS=9.85e-13 RS=4.91e-3 TRS1=2.07e-3 TRS2=2.51e-7 CJO=2.05e-9 TT=4.33e-8)
.MODEL DBKMOD D (RS=1.98e-1 TRS1=2.35E-4 TRS2=-3.83e-6)
.MODEL DPLCAPMOD D (CJO=1.42e-9 IS=1e-30 N=10)
.MODEL MOSMOD NMOS (VTO=3.65 KP=35 IS=1e-30 N=10 TOX=1 L=1u W=1u)
.MODEL RBKMOD RES (TC1=1.23e-3 TC2=-2.34e-7)
.MODEL RDSMOD RES (TC1=5.01e-3 TC2=1.49e-5)
.MODEL RVTOMOD RES (TC1=-5.03e-3 TC2=-5.16e-6)
.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-6.75 VOFF=-2.5)
.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.5 VOFF=-6.75)
.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-2.7 VOFF=2.3)
.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=2.3 VOFF=-2.7)

.ENDS

NOTE: For further discussion of the PSPICE model consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options;** authors, William J. Hepp and C. Frank Wheatley.

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No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.
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